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MCT0144C6W128128PML		MULTI Interface	TFT Module			
(MDT0144ASS-MULTI)		Specification				
Version: 1		Date: 08/07/2021				
	Revision					
1	14/10/2020	First issue				
2	06/07/2021	Updated Brightness				

Display F	eatures		
Display Size	1.44"		
Resolution	128 x 128		
Orientation	Square		
Appearance	RGB		1
Logic Voltage	3.3V		oHS ompliant
Interface	Parallel/ SPI	IVK	$(0) \square \supset$
Brightness	200 cd/m <sup>2</sup>	/ A 23	mpliant
Touchscreen	SPLA	1 00	mpnant
Module Size	32.36 x 38.00 x 2.60mm		1054
Operating Temperature	-20°C ~ +70°C		
Pinout	30 way FFC	Box Quantity	Weight / Display
Pitch	0.5mm		

\* - For full design functionality, please use this specification in conjunction with the ST7735S specification.(Provided Separately)

Display Accessories					
Part Number	Description				

Optional Variants					
Appearances	Voltage				

## **General Description**

### \* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorp hous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 1.44'TFT-LCD contains 128x128pixels, and c an display up to 65K colors.

#### \* Features

-Low Input Voltage: 3.3V (TYP)

-Display Colors of TFT LCD: 65K colors

-RGB Interface: - 8/16-BIT 8080 MCU interface

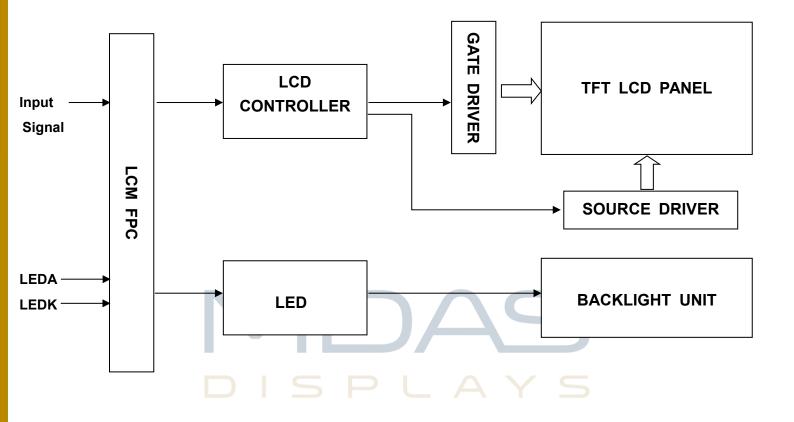
- 3/4-line SPI

General Information	Specification	Unit	Note
Items	Main Panel	Offic	Note
Display area(AA)	25.50(H)*26.50(V) (1.44inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors		colors	-
Number of pixels	128(RGB)*128	dots	-
Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.1992(H)*0.207(V)	mm	-
Viewing angle	MANUE6:00-TURE	_ o'clock_	· -
TFT Driver IC	ST7735S	-	-
Display mode	TN/ Normally white	-	-
Operating temperature	<b>-</b> 20∼+70	${\mathbb C}$	-
Storage temperature	<b>-</b> 30∼+80	${\mathbb C}$	-

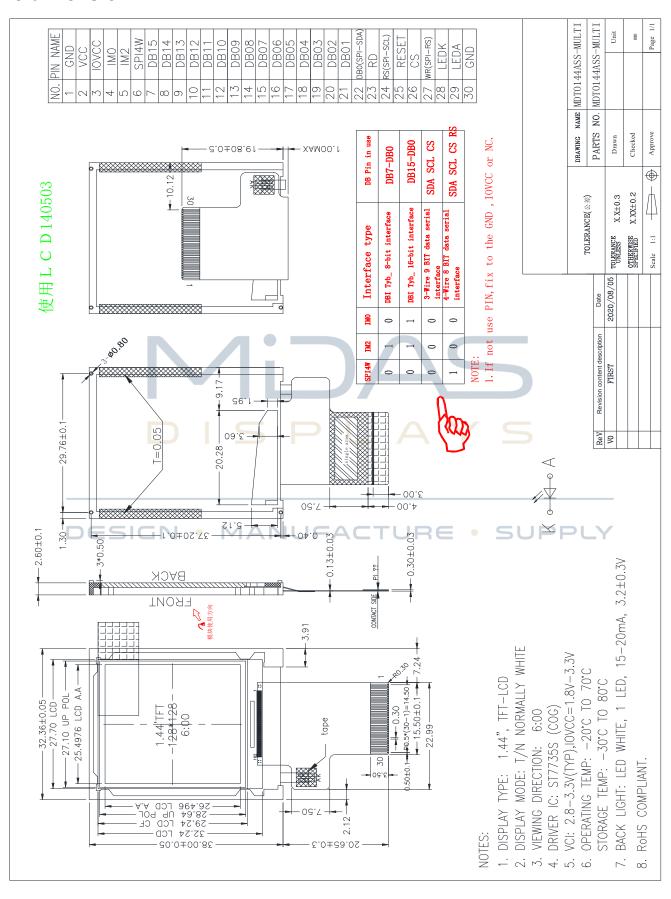
#### \* Mechanical Information

Item		Min.	Тур.	Max.	Unit	Note
Modulo	Horizontal(H)		32.36		mm	-
Module size	Vertical(V)		38.00		mm	-
3120	Depth(D)		2.60		mm	-
	Weight		TBD		g	-

## 1. Block Diagram



### **Outline dimension**



# Input terminal Pin Assignment

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	Р
2	VCC	Supply voltage (3.3V).	Р
3	IOVCC	Supply voltage for I/O.(1.8V-3V)	Р
4	IMO	IM0='1', MCU 8-bit parallel. IM0='0', MCU 16-bit parallel.	
5	IM2	MCU parallel interface and serial interface select. IM2='1', Parallel Interface. IM2='0', Serial Interface.	I
6	SPI4W	<ul> <li>SPI4W='0', 3-line SPI Enable.</li> <li>SPI4W='1', 4-line SPI Enable.</li> <li>If not used, Fix this pin to DGND.</li> </ul>	I
7	DB15		I/O
8	DB14		I/O
9	DB13	DISPLAYS	I/O
10	DB12		I/O
11	DB11		I/O
12	DB10_SI	- DB[15:0] are used as MCU parallel interface data	IPPLYI/O
13	DB09	bus	I/O
14	DB08	- DB0 is the serial input/output signal in serial	I/O
15	DB07	interface mode.	I/O
16	DB06	- In serial interface, DB[15:1] are not used and should be fixed at GND.	I/O
17	DB05		I/O
18	DB04		I/O
19	DB03		I/O
20	DB02		I/O
21	DB01		I/O
22	DB0(SPI-SDA)		I/O
23	RD	Read Enable in 8080 MCU Parallel Interface.	I

24	RS(SPI-SCL)	-Display data/command selection pin in MCU InterfaceRS='1': Display data or parameterRS='0': Command dataIn serial interface, this is used as SCLIf not used, please fix this pin at IOVCC or GND level.	I
25	RESET	This signal will reset the device and must be applied to properly initialize the chip.	I
26	CS	Chip Selection Pin -Low Enable.	I
27	WR(SPI-RS)	-Write enable in MCU parallel interfaceIn 4-line SPI, this pin is used as RS (data/command selection)If not used, please fix this pin at IOVCC or GND.	I
28	LEDK	Cathode pin of backlight.	Р
29	LEDA	Anode pin of backlight.	Р
30	GND	Ground.	Р

# **LCD Optical Characteristics**

## 1. Optical specification

Item		Symbol	Condition	Min.	Тур.	Max.	Unit.	Note
Transmittance (with Polarizer)		T(%)			5			
Contrast R	atio	CR	Θ=0	500	700			
Response	Rising	T <sub>R</sub>	Normal viewing		5	10		
time	Falling	T <sub>F</sub>	angle		15	25	msec	
Color gam	nut	S(%)			40		%	
		Wx		0.263	0.303	0.343		
	White	W <sub>Y</sub>		0.285	0.325	0.365		
		R <sub>X</sub>	1:7	0.555	0.575	0.595		
Color Filter	Red	Ry		0.31	0.33	0.35		
Chromacicity		G <sub>X</sub>		0.321	0.341	0.361		
	Green	G <sub>Y</sub>	SPI	0.578	0.598	0.618		
		Bx		0.132	0.152	0.172		
	Blue	By		0.04	0.06	0.08		
De	≢ŞIGI	N ΘL N	MANUFA	CT <del>U</del> F	€ 60	SUPP	LY	
	Hor.	ΘR			60			
Viewing angle		Θυ	CR>10		30			
	Ver.	Θр			60			
Option View D	irection			6 O'clock	(			

<sup>\*</sup>The data comes from the LCD specification.

### **Measuring Condition**

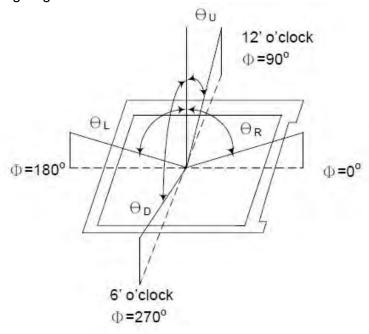
Measuring surrounding : dark room Ambient temperature : 25±2<sub>°</sub>C

15min. warm-up time.

### **Measuring Equipment**

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

### Note (1): Definition of Viewing Angle:

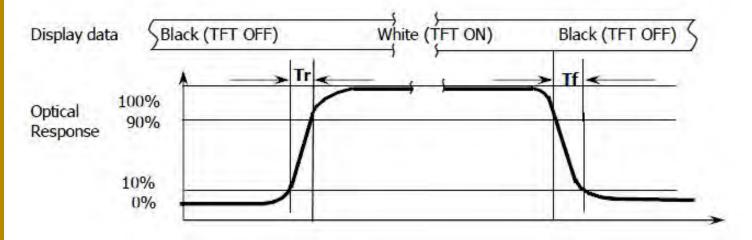


Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

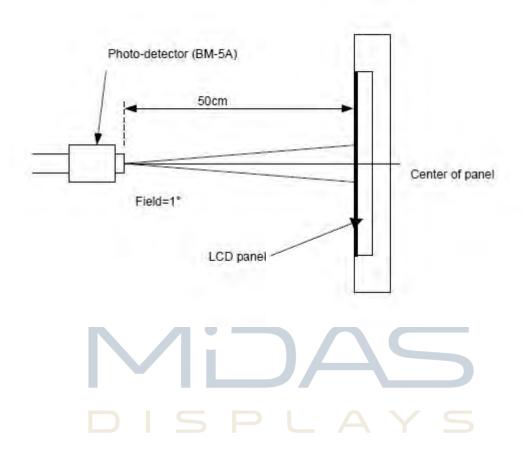
CR = Luminance with all pixels white

Luminance with all pixels black





Note (4): Definition of optical measurement setup



## **Electrical Characteristics**

## 1. Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.8	V
Digital interface supple Voltage	VDDIO	-0.3	4.6	V
Operating temperature	T <sub>OP</sub>	-20	+70	${\mathbb C}$
Storage temperature	T <sub>ST</sub>	-30	+80	$^{\circ}$

### 2. DC Electrical Characteristics

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.4	3.3	4.8	V	
Digital interface supple Voltage	VDDIO	1.65	3.3	4.8	V	
Normal mode Current	MANL	JF <u>A</u> CT	URE 1.2	SUPF	mA	
consumption						
Loyal input valtaga	V <sub>IH</sub>	0.7VDDIO		VDDIO	V	
Level input voltage	V <sub>IL</sub>	GND		0.3VDDIO	V	
Level output valtage	V <sub>OH</sub>	0.8VDDIO		VDDIO	V	
Level output voltage	V <sub>OL</sub>	GND		0.2VDDIO	V	

### 3. LED Backlight Characteristics

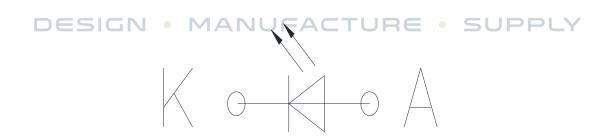
The back-light system is edge-lighting type with 1 chips White LED

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	I <sub>F</sub>	15	20		mA	
Forward Voltage	V <sub>F</sub>		3.2		V	
LCM Luminance	L <sub>V</sub>	200			cd/m2	lf=20mA
LED life time	Hr	50000			Hour	Note1,2
Uniformity	AVg	80			%	

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

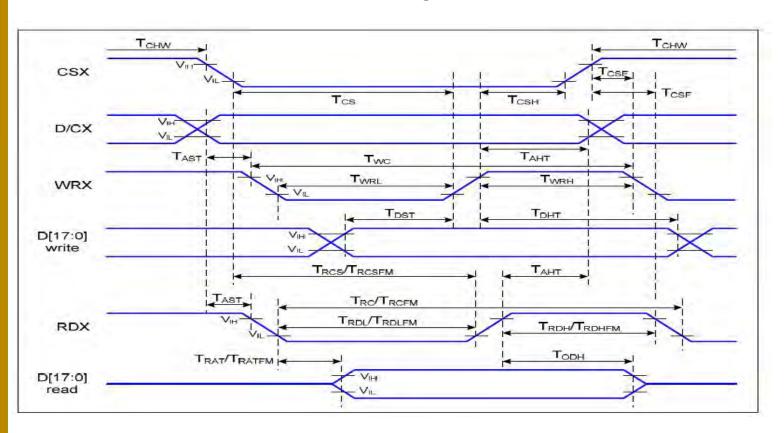
Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=20mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



### **AC Characteristic**

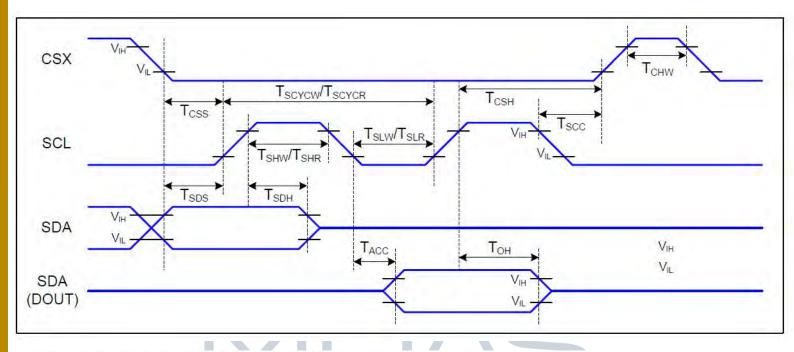
# 1. 8080 Series MCU Parallel Interface Timing Characteristics: 16/8-bit Bus



Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	Min	Max	Unit	Description
DICY	TAST	Address Setup Ttime	0		ns	
D/CX	TAHT	Address Hold Time (Write/Read)	10		ns	100 <del>-5</del> .
	TCHW	Chip Select "H" Pulse Width	0		ns	
	TCS	Chip Select Setup Time (Write)	15		ns	
CSX	TRCS	Chip Select Setup Time (Read ID)			ns	
CSA	TRCSFM	Chip Select Setup time (Read FM)	355		ns	100 <del>5</del> -
	TCSF	Chip Select Wait Time (Write/Read)	10		ns	
	TCSH	Chip Select Hold Time	10		ns	
	TWC	Write Cycle	66		ns	
WRX	TWRH	Control Pulse "H" Duration	15		ns	
	TWRL	Control Pulse "L" Duration	15		ns	
	TRC	Read Cycle (ID)	160		ns	
RDX (ID)	TRDH	Control Pulse "H" Duration (ID)	90		ns	When Read ID Data
	TRDL	Control Pulse "L" Duration (ID)	45		ns	

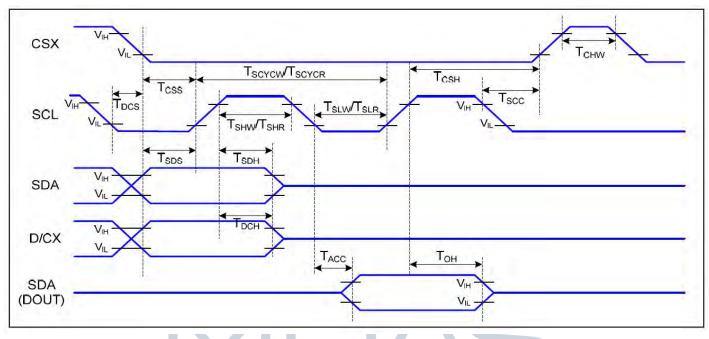
# 2. Serial Interface Characteristics (3-line Serial)



Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	Min	Max	Unit	Description	
	TCSS	Chip Select Setup Time (Write)	15		ns		
	TCSH	Chip Select Hold Time (Write)	15		ns		
CSX	TCSS	Chip Select Setup Time (Read)	60		ns	]	
	TSCC	Chip Select Hold Time (Read)	65		ns	1	
	TCHW	Chip Select "H" pulse width	40		ns		
	TSCYCW	Serial Clock Cycle (Write)	66		ns		
	TSHW	SCL "H" Pulse Width (Write)	15		ns	1	
SCL	TSLW	SCL "L" Pulse Width (Write)	15		ns		
SCL	TSCYCR	Serial Clock Cycle (Read)	150		ns		
	TSHR	SCL "H" Pulse Width (Read)	60		ns		
	TSLR	SCL "L" Pulse Width (Read)	60		ns		
	TSDS	Data Setup Time	10		ns		
SDA	TSDH	Data Hold Time	10		ns	For Maximum CL=30pF	
(DIN)	TACC	Access Time	10	50	ns	For Minimum CL=8pF	
(DOUT)	ТОН	Output Disable Time	15	50	ns		

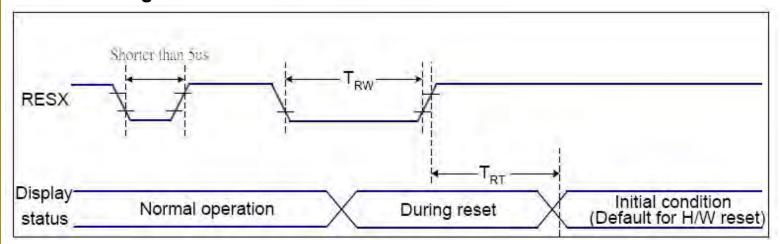
# 3. Serial Interface Characteristics (4-line Serial)



Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	TCSS	Chip Select Setup Time (Write)	45		ns	
	TCSH	Chip Select Hold Time (Write)	45		ns	
CSX	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65		ns	
	TCHW	Chip Select "H" Pulse Width	40		ns	
	TSCYCW	Serial Clock Cycle (Write)	66		ns	Wester Communication
	TSHW	SCL "H" Pulse Width (Write)	15		ns	-Write Command &
0.01	TSLW	SCL "L" Pulse Width (Write)	15		ns	Data Ram
SCL	TSCYCR	Serial Clock Cycle (Read)	150		ns	D1010
	TSHR	SCL "H" Pulse Width (Read)	60		ns	-Read Command &
	TSLR	SCL "L" Pulse Width (Read)	60		ns	- Data Ram
DIOV	TDCS	D/CX Setup Time	10		ns	
D/CX	TDCH	D/CX Hold Time	10		ns	
004	TSDS	Data Setup Time	10		ns	
SDA	TSDH	Data Hold Time	10		ns	For Maximum CL=30pF
(DIN)	TACC	Access Time	10	50	ns	For Minimum CL=8pF
(DOUT)	ТОН	Output Disable Time	15	50	ns	

## 4. Reset Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

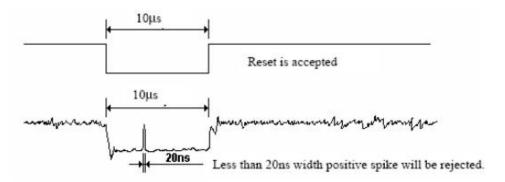
Related Pins	Symbol	Parameter	MIN	MAX	Unit
2	TRW	Reset pulse duration	10	<del>,7</del> 9	us
RESX	TDT	Depat sancel	420	5 (Note 1, 5)	ms
	TRT	Reset cancel	120 (Note 1, 6, 7)		ms

#### Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
  - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
  - 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for
   120msec.



## **LCD Module Out-Going Quality Level**

### 1. VISUAL & FUNCTION INSPECTION STANDARD

### 1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

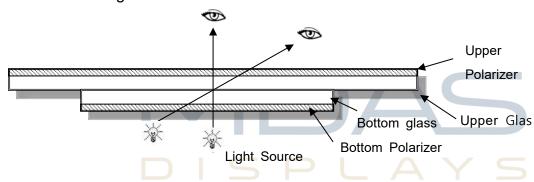
Temperature : 25±5℃

Humidity: 65%±10%RH

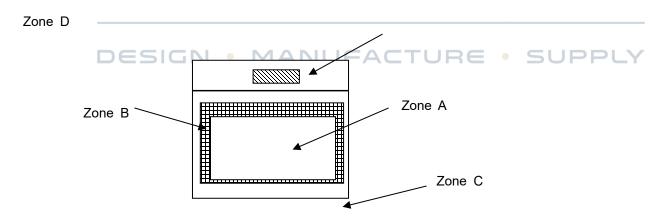
Viewing Angle: Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



#### 1.2 Definition



Zone A: Effective Viewing Area (Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A+Zone B) which can not be seen after assembly by customer.)

Zone D: IC Bonding Area

#### Note:

As a general rule, visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

## 1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class  $\,\,\mathrm{II}\,\,$  AQL:

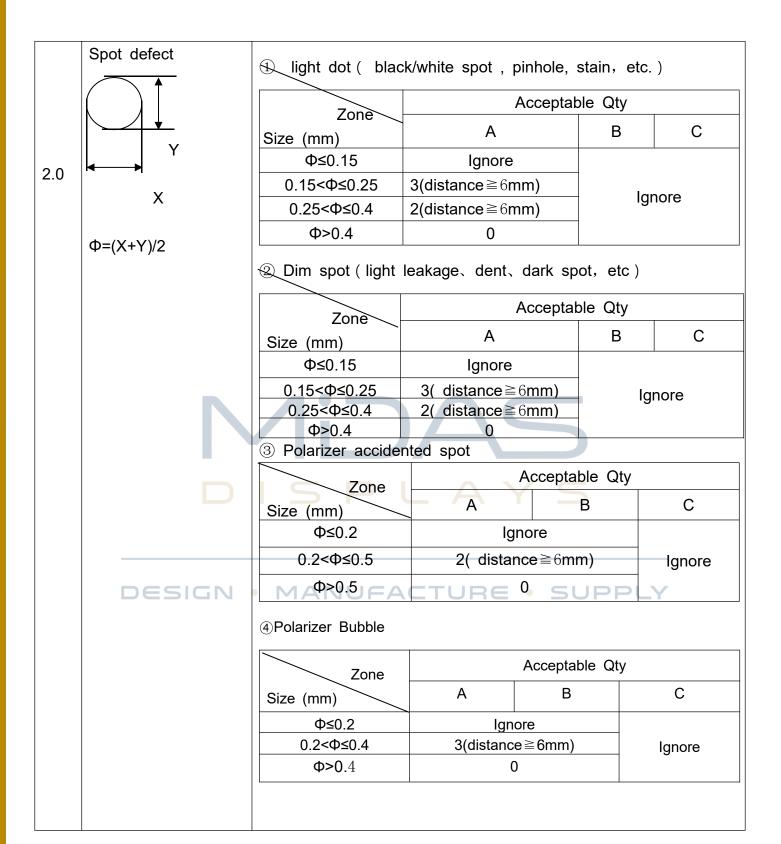
Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display, TP: Touch Panel, LCM: Liquid Crystal Module

No	Items to be insp	Criteria	Classification of de		
	ected		fects		
		1) No display, Open or miss line			
1	Functional defects	2) Display abnormally, Short			
'	Functional defects	3) Backlight no lighting, abnormal lighting.			
			Major		
2	Missing	Missing component			
3	Outline dimension	Overall outline dimension beyond the drawi			
3	Outline dimension	ng is not allowed			
4	Color tone	Color unevenness, refer to limited sample			
5	Soldering appeara	Good soldering, Peeling off is not allowed.	Minor		
)	nce	ISPLAY	Minor		
6	LCD/Polarizer	Black/White spot/line, scratch, crack, etc.			

# 1.4 Criteria (Visual)

Number	Items	Criteria(mm)		
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height	(1) The edge of LCD broken			
L: Length of IT		X Y Z		
O, T: Height of LCD		≤3.0mm <inner border="" he="" line="" of="" seal="" t="" td="" ≤t<=""></inner>		
	(2)LCD corner broken	X Y Z ≤3.0mm ≤L ≤T		
DES		JFACTURE • SUPPLY		
	(3) LCD crack	Crack Not allowed		



3.0	LCD Pixel defect	Pixel bad po	ints	
		Item	Zone A	Acceptable Qt
			Random	N≤2
		Bright dot	2 dots adjacent	N≤0
			3 dots adjacent	N≤0
			Random	N≤2
		Dark dot	2 dots adjacent	N≤0
			3 dots adjacent	N≤0
		Distance	<ol> <li>Minimum Distance Between Bright dots.</li> <li>Minimum Distance Between dark dots</li> <li>Minimum Distance Between dark and bright dot.</li> </ol>	5mm
		Total bright	N≤4	
	DESIGN	LCD pane B) Dark dot: LCD pane		size in which , blue picture.

	Line defect (LCD /Polarizer backlight bla		Length(m	Acce	ptable C	Qty	
	ck/white line, scratch,	Width(mm)	m)	А	В	С	
	stain)	Ф≤0.03	Φ≤0.03 Ignore Ign				
4.0		0.03 <w≤0.04< td=""><td>L≤3.0</td><td colspan="2" rowspan="2">N≤2 Igr N≤1</td><td>Ignore</td></w≤0.04<>	L≤3.0	N≤2 Igr N≤1		Ignore	
	Ψ W: width, L: length	0.04 <w≤0.05< td=""><td>L≤2.0</td><td></td></w≤0.05<>	L≤2.0				
	N : Count	W>0.05	W>0.05 Define as spot defect				
	Electronic Componen	Not allow missing pa				older joint, mi	
5.0	ts SMT.	smatch, The positive	and negative	е роганту оррс	osite		
6.0	Display color& Brigh	Color: Measuring the color coordinates, The measurement start rd according to the datasheet or samples.					
0.0	tness.  2. Brightness: Measuring the brightness of White screen, The urement standard according to the datasheet or Samples.						
7.0	LCD Mura/Waving/ Not visible through 5% ND filter in 50% gray or judge by limit so				by limit sampl		
	Hot spot						
	DESIGN	<ul><li>MANUFA</li></ul>	CTUR	E • SU	PPL	_Y	

## Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed

# **Reliability Test Result**

Item	Condition	Inspection after test
High Temperature Operating	70°C,96H	
Low Temperature Operating	-20°C, 96HR	
High Temperature Storage	80°C, 96HR	
Low Temperature Storage	-30°C, 96HR	Inspection after 2~4hours storage at room temperature, the
High Temperature & High	+60°C, 90% RH ,96 hours.	sample shall be free from
Humidity Operating		defects:
Thermal Shock (Non-	-10°C,30 min ↔ +60°C,30 min,	1.Air bubble in the LCD;
operation)	Change time:5min 20CYC.	2.Non-display;
	C=150pF, R=330,5points/panel	3.Missing segments/line;
ESD test	Air:±8KV, 5times; Contact:±6KV, 5 times;	4.Glass crack;
DESIG	(Environment. 13 C~39 C, 30 %~60 %).	5.Current IDD is twice higher
	Frequency range:10~55Hz, Stroke:1.5mm	than initial value.
Vibration (Non-operation)	Sweep:10Hz~55Hz~10Hz 2 hours for each direction of	
	X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

#### Remark:

- 1. The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance >  $10M\Omega$ ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

- 5. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
- 6. The color fading mura of polarizing filter should not care.

### **Cautions and Handling Precautions**

### 1. Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
- Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
- If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
- Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

#### 2. Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
- It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
- In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

